



MMDT2907A

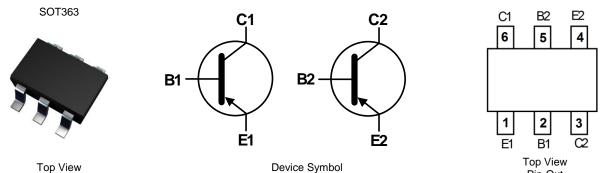
60V DUAL PNP SMALL SIGNAL TRANSISTOR IN SOT363

Features

- Ultra-Small Surface Mount Package
- **Epitaxial Planar Die Construction**
- Ideal for Low Power Amplification and Switching
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish --- Matte Tin Finish. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)



Pin-Out

Ordering Information (Notes 4 & 5)

Part number	Status	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMDT2907A-7-F	NRND	AEC-Q101	K2F	7	8	3,000
MMDT2907A-7	Active	AEC-Q101	K2F	7	8	3,000
MMDT2907AQ-7-F	Active	Automotive	K2F	7	8	3,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

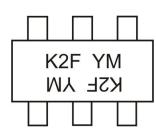
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/product_compliance_definitions.html.

5. NRND = Not Recommended for New Design. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



K2F = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Notes:

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Year	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021
Code	Х	Y	Z	A	В	С	D	E	F	G	Н	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-60	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	Ι _C	-600	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	200	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C

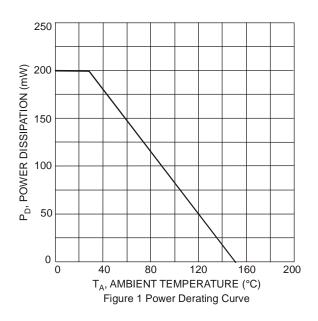
ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 6. For the device mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS					•	1
Collector-Base Breakdown Voltage	BV _{CBO}	-60	_	_	V	$I_{\rm C} = -10 \mu A, I_{\rm B} = 0$
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	-60	—	—	V	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	—	_	V	$I_{E} = -10\mu A, I_{C} = 0$
Collector Cutoff Current	I _{СВО}	_	_	-10 -10	nΑ μΑ	$V_{CB} = -50V, I_E = 0$ $V_{CB} = -50V, I_E = 0, T_A = +125^{\circ}C$
Collector Cutoff Current	ICEX	_	—	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -0.5V$
Base Cutoff Current	I _{BL}	_	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -0.5V$
ON CHARACTERISTICS (Note 8)			•			· · · ·
DC Current Gain	h _{FE}	75 100 100 100 50		 300 	_	$\begin{split} I_{C} &= -100 \mu A \ , V_{CE} &= -10V \\ I_{C} &= -1.0 m A, \ V_{CE} &= -10V \\ I_{C} &= -10 m A, \ V_{CE} &= -10V \\ I_{C} &= -150 m A, \ V_{CE} &= -10V \\ I_{C} &= -500 m A, \ V_{CE} &= -10V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	-0.4 -1.6	V	$I_{C} = -150 \text{mA}, I_{B} = -15 \text{mA}$ $I_{C} = -500 \text{mA}, I_{B} = -50 \text{mA}$
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	_	-1.3 -2.6	V	$I_{C} = 150 \text{mA}, I_{B} = 15 \text{mA}$ $I_{C} = 500 \text{mA}, I_{B} = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					•	
Output Capacitance	Сово	—	—	8.0	pF	$V_{CB} = -10V$, f = 1.0MHz, I _E = 0
Input Capacitance	CIBO	—	—	30	pF	$V_{EB} = -2.0V$, f = 1.0MHz, I _C = 0
Current Gain Bandwidth Product	f _T	200	—	—	MHz	$V_{CE} = -20V, I_C = -50mA, f = 100MHz$
SWITCHING CHARACTERISTICS			•			
Turn-On Time	t _{off}	_	—	45	ns	$V_{CC} = -30V$, $I_{C} = -150mA$,
Delay Time	t _d	_		10	ns	$V_{CC} = -50V, I_C = -150IIA,$ $I_{B1} = -15mA$
Rise Time	tr	_	—	40	ns	
Turn-Off Time	t _{off}	_	—	100	ns	V _{CC} = -6V, I _C = -150mA,
Storage Time	ts	_	—	80	ns	$V_{CC} = -6V$, $I_C = -15000$ A, $I_{B1} = -I_{B2} = -15$ mA
Fall Time	t _f	—	—	30	ns	1B1 - 1B2 = -1000A

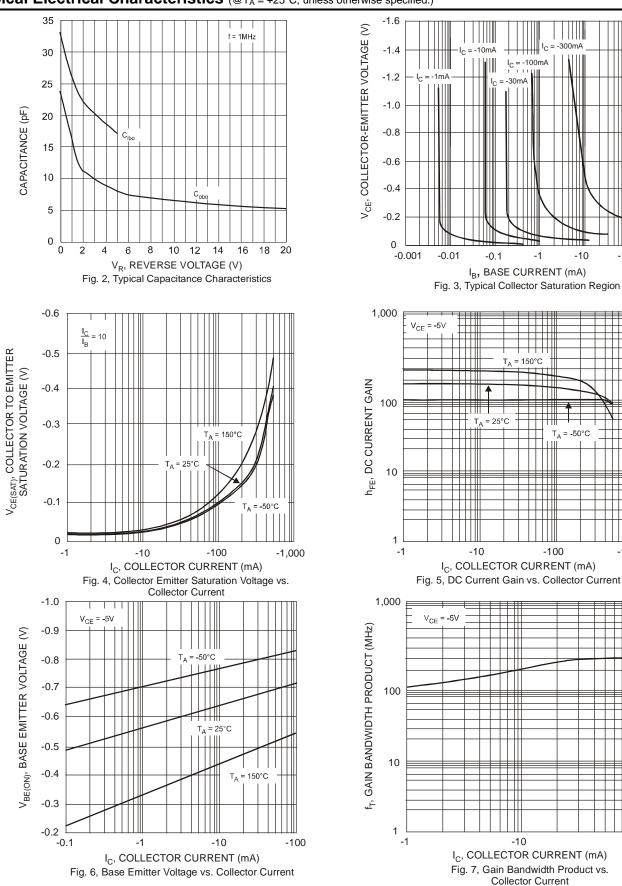
Note: 8. Short duration pulse test used to minimize self-heating effect.



-100

-1,000

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

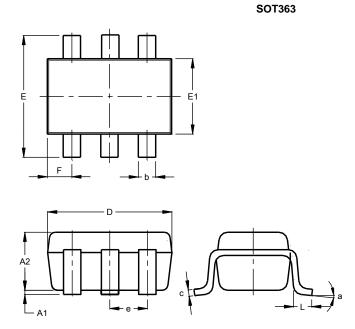


-100



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

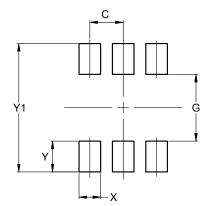


	50	T363					
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	1.00				
b	0.10	0.30	0.25				
c	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C).650 B	SC				
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а		8°					
All	Dimen	sions	in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

SOT363



Dimensions	Value (in mm)
С	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500



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